

MXD8631

0.1-3.0GHz SP3T Switch



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General Description

The MXD8631 is a CMOS silicon-on-insulator (SOI), single-pole, triple-throw (SP3T) receive switch. The high linearity performance and low insertion loss makes the device an ideal choice for GSM/WCDMA/LTE handset and data card applications.

The MXD8631 SP3T switch is provided in a compact Quad Flat No-Lead (QFN) 1.15mm x 1.15mm x 0.55mm package. A functional block diagram is shown in Figure 1. The pin configuration and package are shown in Figure 2. Signal pin assignments and functional pin descriptions are provided in Table 1.

Applications

- GSM/WCDMA/LTE receive
- 802.11a/b/g/n WLANs

Features

- Broadband frequency range: 0.1 to 3.0 GHz
- Low insertion: 0.50 dB @ 2.7 GHz
- High isolation: 25 dB up to 2.7 GHz
- No external DC blocking capacitors required
- Positive low voltage control: VC = 1.6 to 3.00
 V, VDD = 2.5 to 3.0 V
- Small, QFN (9-pin, 1.15mm x 1.15mm x 0.55mm) package



Figure 1.Functional Block Diagram



Figure 2.Pin-out (Top View)

Functional Block Diagram and Pin Function

Application Circuit



Figure 3. MXD8631 Application Circuit

Table 1. Pin Description

Pin No.	Name	Description	Pin No.	Name	Description
1	V1	Control Pin 1	6	GND	Ground
2	RF3	RF-Port 3	7	VDD	Power Supply
3	RF1	RF-Port 1	8	V2	Control Pin 2
4	RFin	RF Input	9	GND	Ground
5	RF2	RF-Port 2			

Truth Table

Table 2.

V1	V2	Active Path
0	0	OFF
1	0	ANT to RF1
0	1	ANT to RF2
1	1	ANT to RF3

Note: "1" = 1.0 V to 3.00 V. "0" = -0 V to +0.3 V.

Recommended Operation Range

Table 3.

Parameters	Symbol	Min	Тур	Max	Units
Operation Frequency	f1	0.1	-	3.0	GHz
Power supply	V _{DD}	2.5	2.8	3.0	V
Switch Control Voltage High	V _{CTL_H}	1.6	1.8	3.0	V
Switch Control Voltage Low	V _{CTL_L}	0	0	0.3	V

Specifications

Table 4.Electrical Specifications

Doromotor	Symbol	Specification			Unite	Test Condition	
Parameter		Min.	Typical	Max.	Units	Test Condition	
DC Specifications							
Control voltage: Low High	V _{ctl_l} V _{ctl_h}	0 1.60	+1.8	0.3 3.00	V V		
Supply voltage	V _{DD}	2.5	2.8	3.0	V		
Supply current	IDD		20		uA	VDD = 2.8 V	
Control current	Ictl		1		uA	VC= 1.8 V	
RF Specification	s		• •		•		
Insertion loss	IL		0.30 0.40 0.50	0.40 0.50 0.60	dB dB dB	0.8 to 1.0 GHz 1.0 to 2.2 GHz 2.2 to 3.0 GHz	
Isolation	ISO	30 24 20	35 28 24		dB dB dB	0.8 to 1.0 GHz 1.0 to 2.2 GHz 2.2 to 3.0 GHz	
Return loss	S11		15		dB	0.8 to 3.0 GHz	
3rd Order Input Intercept Point	IIP3	+60	+70		dBm	0.8 to 3.0 GHz, $\Delta F = 1$ MHz, PIN = +20 dBm/tone	
Input 0.1 dB compression point	P0.1dB		+29		dBm	0.8 to 3.0 GHz	
2nd harmonic	2fo		+83		dBc	0.8~3GMHz, PIN = +26 dBm	
3rd harmonic	3fo		+70		dBc	0.8~3GMHz, PIN = +26 dBm	
Switching on time			100		ns	50% VCTL to 10/90% RF	
Switching off time			100		ns	50% VCTL to 90/10% RF	
Startup time			300		ns	Shutdown state to any RF switch state	

Absolute Maximum Ratings

Table 5. Maximum ratings

Parameters	Symbol	Minimum	Maximum	Units
Supply voltage	V _{DD}	+2.5	+3.0	V
Digital control voltage	V _{CTL}	0	+3.0	V
RF input power	P _{IN}		+29	dBm
Operating temperature	T _{OP}	-30	+85	°C
Storage temperature	T _{STG}	-55	+150	°C
Electrostatic discharge: Human Body Model (HBM), Class 1C Machine Model (MM), Class A	ESD		2000 100	v v

Note: Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal value. Exceeding any of the limits listed here may result in permanent damage to the device.

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Package Outline Dimension





TOP VIEW



DECODIDENCI	SYMBOL	MILLIMETER			
DESCRIPTION	STIVIDOL	MIN	NOM	MAX	
TOTAL THICKNESS	A	0.50	0.55	0.60	
STAND OFF		A1	0.00		0.05
MOLD THICKNESS	A2	0.35	0.40	0.45	
L/F THICKNESS	A3	0.150 REF			
LEAD WIDTH	b	0.10	0.20	0.30	
BODY SIZE	х	D	1.10	1.15	1.20
BODT SIZE	Y	E	1.10	1.15	1.20
LEAD PITCH		е	0.40 BSC		
LEAD LENGTH		L	0.10	0.20	0.30
PACKAGE EDGE TOLERA	ANCE	aaa		0.1	
MOLD FLATNESS	bbb	0.1			
COPLANARITY	ccc	0.08			
LEAD OFFSET	ddd	0.1			
EXPOSED PAD OFFSET	eee	0.1			

Figure 4. Package outline dimension



gure 5. Recommended Lead-Free Reflow Profile

Table 6.

Profile Parameter	Lead-Free Assembly, Convection, IR/Convection			
Ramp-up rate $(TS_{max} to T_p)$	3°C/second max.			
Preheat temperature $(TS_{min} \text{ to } TS_{max})$	150°C to 200°C			
Preheat time (t_s)	60 - 180 seconds			
Time above TL , 217 $^\circ\!\!{\rm C}$ (t_L)	60 - 150 seconds			
Peak temperature (Tp)	260 ℃			
Time within 5 $^\circ\!\mathrm{C}$ of peak temperature(t_p)	20 - 40 seconds			
Ramp-down rate	6°C/second max.			
Time 25 $^\circ C$ to peak temperature	8 minutes max.			

ESD Sensitivity

Integrated circuits are ESD sensitive and can be damaged by static electric charge. Proper ESD protection techniques should be used when handling these devices.

RoHS Compliant

This product does not contain lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE), and are considered RoHS compliant.

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